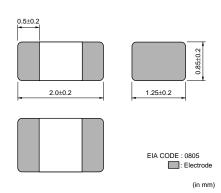
Data Sheet

EMIFIL® (Inductor type) Chip Ferrite Bead

BLM21P Series (0805 Size)

Dimensions



Equivalent Circuit

()

1

(Resistance element becomes dominant at high frequencies.)

Packaging

Code	Packaging	Minimum Quantity	
D	180mm Paper Tape	4000	
J	330mm Paper Tape	10000	
В	Bulk(Bag)	1000	

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance (max.)	Operating Temperature Range
BLM21PG220SN1	22ohm±25%	-	6000mA	0.01ohm	-55 to +125°C
BLM21PG300SN1	30ohm(Typ.)	-	3000mA	0.015ohm	-55 to +125°C
BLM21PG600SN1	60ohm±25%	-	3000mA	0.025ohm	-55 to +125°C
BLM21PG121SN1	120ohm±25%	-	3000mA	0.03ohm	-55 to +125°C
BLM21PG221SN1	220ohm±25%	-	2000mA	0.050ohm	-55 to +125°C
BLM21PG331SN1	330ohm±25%	-	1500mA	0.09ohm	-55 to +125°C

Number of Circuits: 1

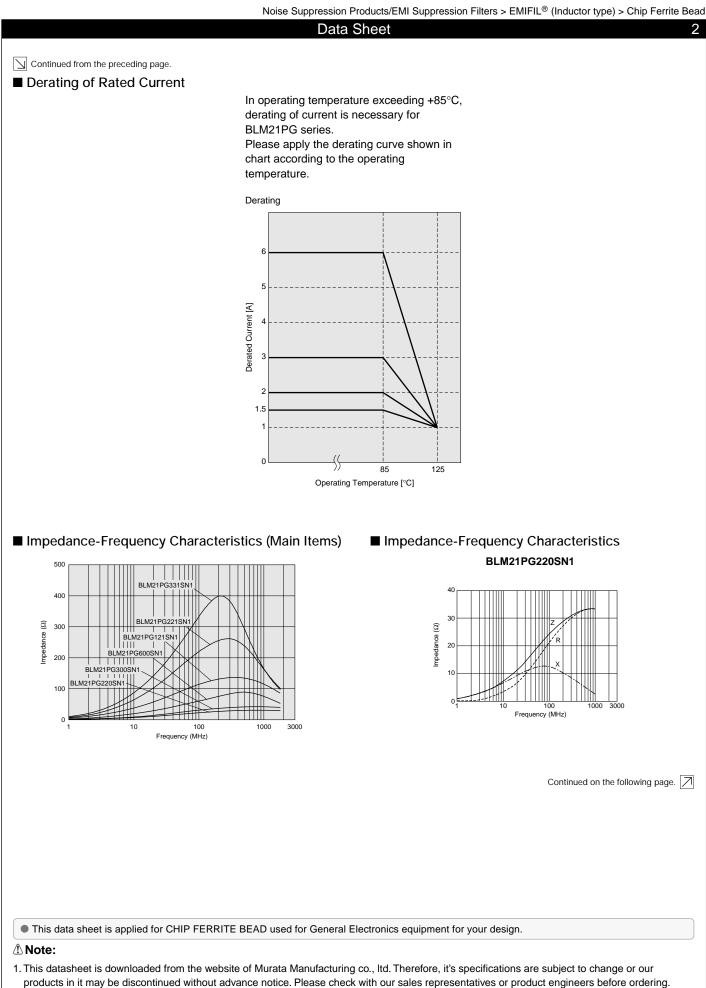
Continued on the following page.

• This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

A Note:

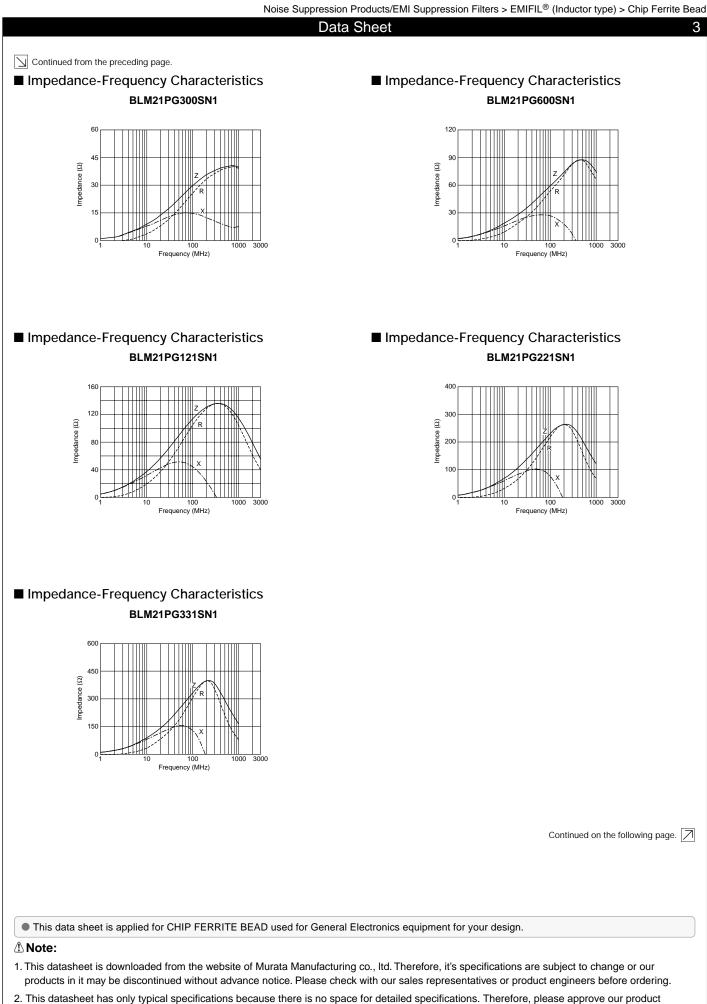
1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.

2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.



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Data Sheet

Continued from the preceding page.

■ ①Caution/Notice

ACaution (Rating)

Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use. 4

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